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120-37A/B-187

LOW DENSITY, HIGH TEMPERATURE RESISTANT, LOW SHRINKAGE, EPOXY
POTTING COMPOUND

DESCRIPTION: 120-37 is a low density, high temperature resistant, low shrink, syntactic foam, two component, epoxy potting and encapsulating compound. Product is designed to release entrapped air rapidly during cure, resulting in a smooth, pinhole free surface. 120-37 provides a combination of low density, minimal shrinkage and high temperature resistance.

Table with 4 columns: Part A, Part B-187, Mixture, and a fourth column. Rows include Appearance, Viscosity, Mix Ratio (By Weight), and Pot Life 100 gram mass.

MIXING INSTRUCTIONS: Premix Part A in original container prior to adding curing agent. Add Part B to Part A and mix until uniform. NOTE: Due to the purity of the materials it is not unusual for crystallization of the part A and or part B to occur. Warm to 40-45°C in a water bath to return the material to its original viscosity. The crystallization of the resin and or catalyst does not effect the performance of the product in any way.

CURING INSTRUCTIONS:

Table with 2 columns: Handling Properties and Full Cure. Values include 1 hour @ 60°C and 1 hr @ 60°C + a post cure of 1hr @ 125°C.

TYPICAL CURED PROPERTIES:

Table with 2 columns: Property and Value. Properties include Specific Gravity, Hardness, Coef. of Therm. Exp., Cure Shrinkage, Heat Distortion Temp., Tensile Strength, Water Absorption, Dielectric Strength, Volume Resistivity, Power Factor, and Dielectric Constant.

STORAGE: Shelf life: 12 months at 25°C, in unopened, unmixed containers.

SAFETY & HANDLING: Use with adequate ventilation. Keep away from sparks and open flames. Avoid prolonged contact with skin and breathing of vapors. Wash with soap and water to remove from skin.

All technical information is based on data obtained by CMI personnel and is believed to be reliable. No warranty is either expressed or implied with respect to results or possible infringements on patents.

REVISION DATE: 6/10/08 REVISION: B